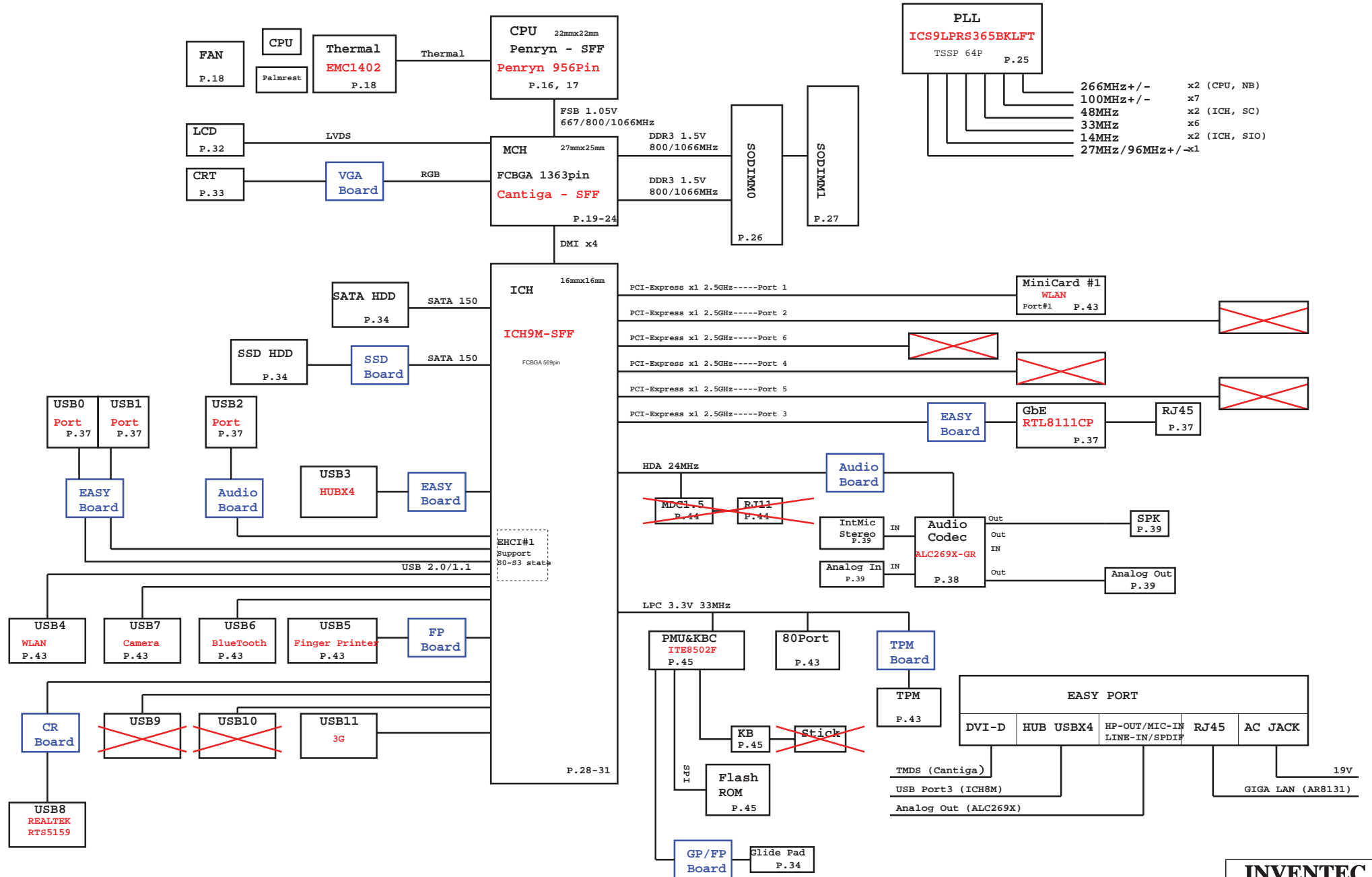


1. Schematic Page Description :

Montevina Schematic Ver : X01

- | | |
|----------------------------------|---------------------------------|
| 1. Title | 24. Clock Generator |
| 2. Schematic Page DESCR | 25. DDR3 SDRAM SO-DIMM0 |
| 3. Block Diagram | 26. DDR3 SDRAM SO-DIMM1 |
| 4. Annotations | 27. ICH9M CPU/IDE/SATA(1/4) |
| 5. Schematic Modify | 28. ICH9M PCI/PCIE/DMI/USB(2/4) |
| 6. Timing Diagram | 29. ICH9M GPIO(3/4) |
| 7. Power Block Diagram | 30. ICH9M Power/GND(4/4) |
| 8. Adaptor in/Charge | 31. LCD CNN/SATA/3G/WLAN |
| 9. 5VLA/5VA/3VA | 32. KBC ITE8512F |
| 10. 3VS/5VS/1.5V (DDR3) | 33. IO CN |
| 11. 1.05VS/1.5S/1.8V/1.5VA | |
| 12. Power Latch/1.5VS/SCREW HOLE | |
| 13. CPU Core Power | |
| 14. GPU Core Power | |
| 15. Penryn Processor(1/2) | |
| 16. Penryn Processor(2/2) | |
| 17. CPU Thermal | |
| 18. Cantiga Host(1/6) | |
| 19. Cantiga DMI/Graph(2/6) | |
| 20. Cantiga DDRII(3/6) | |
| 21. Cantiga Power(4/6) | |
| 22. Cantiga Power(5/6) | |
| 23. Cantiga Ground(6/6) | |

3. Block Diagram :



<http://laptop-motherboard-schematic.blogspot.com/>

INVENTEC			
TITLE BAP31 (Penryn+Cantiga+ICH9M)SFF Block Diagram			
SIZE Custom	CODE X01	DOC-NUMBER D-CS-1310A2264501A1G	REV X01
CHANGE by Miles Lu		DATE Tuesday, March 10, 2008	SHEET 3 of 36

4. Net name Description :

Voltage Rails

DCIN	Primary DC system power supply
+5VLA	5.0V always on power rail by LATCH or ACIN
+5VA	5.0V always on power rail by ECPWON
+3VA	3.3V always on power rail by ECPWON
+5VS	5.0V switched power rail by SLP_S3#_3R
+3VS	3.3V switched power rail by SLP_S3#_3R
+1.8VS	1.8V switched power rail by SLP_S3#_3R

VCC_CORE	Core Voltage for CPU
+1.05VS	1.05V power rail for AGTL+ termination/Core for GMCH by SLP_S3#_3R
+1.25VS	1.25V switched power rail by SLP_S3#_3R
+1.5VS	1.5V power rail for CPU PLL/DMI;PCIE;DDRIII DLLs for GMCH/Core;PCIE for ICH9m by SLP_S3#_3R

+1.5V	1.5V power rail for DDRII by SLP_S5#_3R
0.75VDDT_DDRIII	0.75V DDRII Termination Voltage by SLP_S3#_3R

Part Naming Conventions

C	= Capacitor
CN	= Connector
D	= Diode
F	= Fuse
L	= Inductor
Q	= Transistor
R	= Resistor
RP	= Resistor Pack
U	= Arbitrary Logic Device
Y	= Crystal and Osc

Net Name Suffix

= Active Low signal

5. Board Stack up Description

PCB Layers

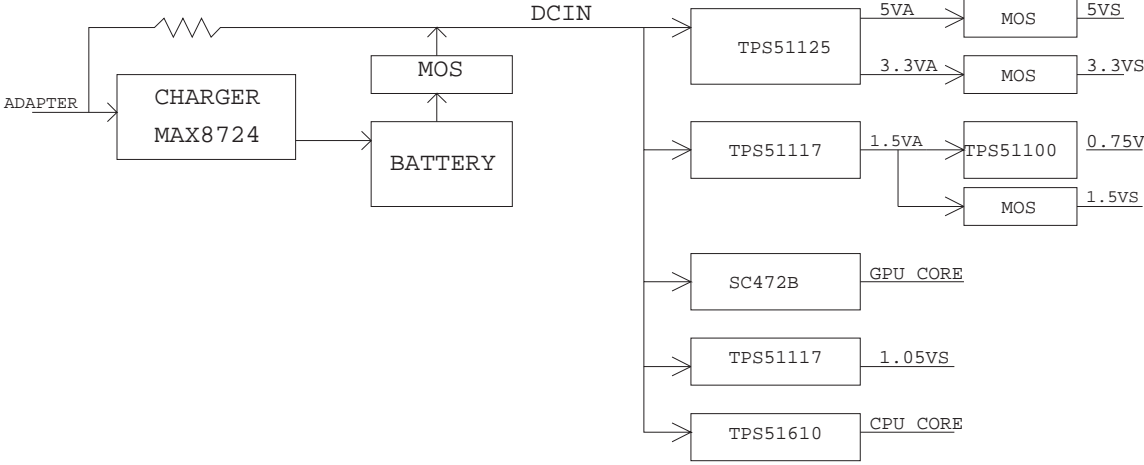
Layer 1		Component Side, Microstrip signal Layer
Layer 2		Ground Plane
Layer 3		Stripline Layer
Layer 4		Power Plane
Layer 5		Stripline Layer
Layer 6		Stripline Layer
Layer 7		Ground Plane
Layer 8		Solder Side, Microstrip signal Layer

	Differential Impedance for Microstrip	Differential Impedance for Stripline
Host Clock	95 ohm +/- 20%	95 ohm +/- 20%
PCI-E Clock	95 ohm +/- 20%	95 ohm +/- 20%
DDR3 CLK	75 ohm +/- 20%	75 ohm +/- 20%
DDR3 Strobe	90 ohm +/- 20%	90 ohm +/- 20%
DMI Bus	95 ohm +/- 20%	95 ohm +/- 20%
PCIE Bus	95 ohm +/- 20%	95 ohm +/- 20%
SDVO	95 ohm +/- 20%	95 ohm +/- 20%
SATA	95 ohm +/- 20%	95 ohm +/- 20%
USB	90 ohm +/- 20%	90 ohm +/- 20%
LVDS	95 ohm +/- 20%	95 ohm +/- 20%
Lan	95 ohm +/- 20%	95 ohm +/- 20%

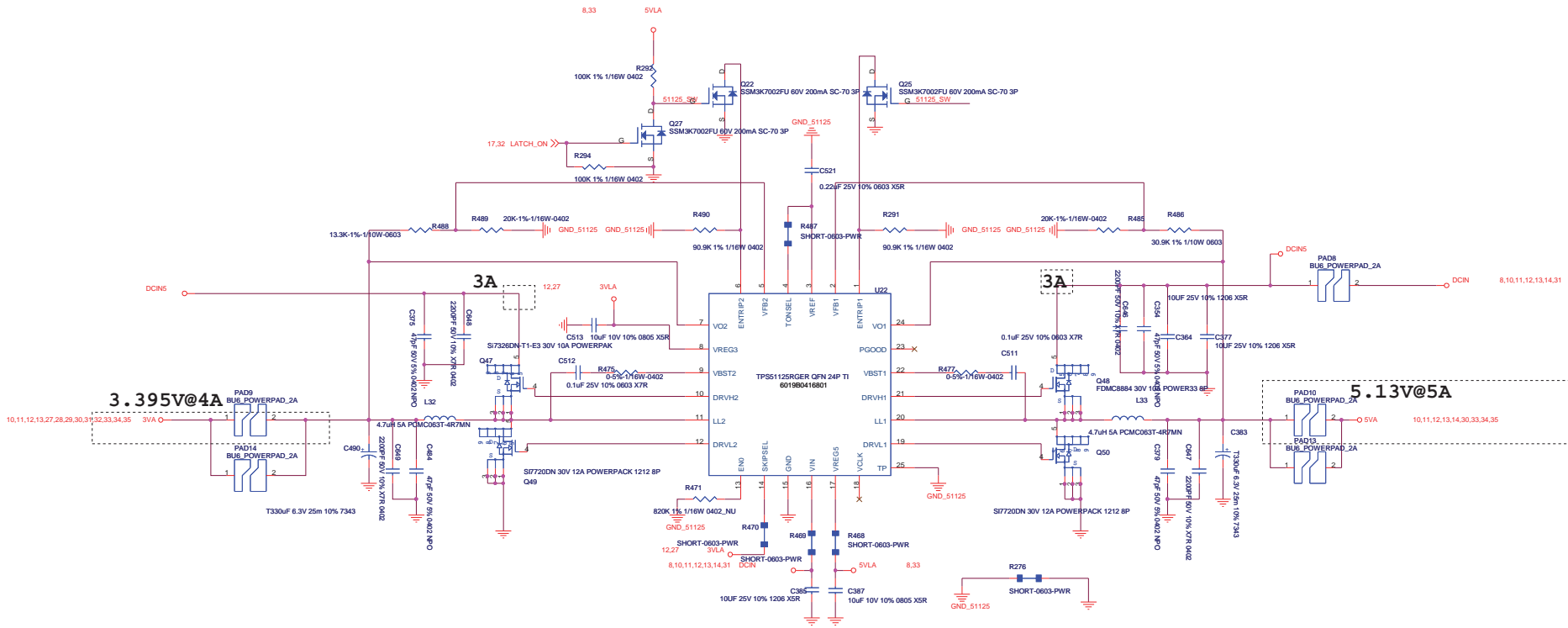
Power Rail	Destination	Voltage	SO Current
VCC_CORE	Penryn SFF HFM: LFM:	1.3319V-1.4375V-1.4591V 0.9221V-0.9625V-0.9739V	18A
1.05VS	Penryn SFF : AGTL+ termination Cantiga GS: Core Cantiga GS: PCIE Cantiga GS:Core+HMEI+HSIO Cantiga GS:VCC_GMCH Cantiga GS:VCCA_SM_CK and NCTF Cantiga GS:VCC_DMI Cantiga GS:VCCA_SM Cantiga GS:VTT ICH9M:VCC1_05 ICH9M:DMI ICH9M:CPU_IO	1V-1.05V-1.10V 0.997V-1.05V-1.102V 0.9975V-1.05V-1.1025V 0.9975V-1.05V-1.1025V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V 0.997V-1.05V-1.102V	4.5A 8.7A 1.78A 2.898A 10.154A 37.95mA 456mA 747.5mA 852mA 1.634A 48mA 2mA
1.5VS	Penryn SFF PLL Cantiga GS: QDAC Cantiga GS: LVDS Cantiga GS: TVDAC Cantiga GS: Various PLLS analog supply Cantiga GS: VCC_SM_CK Cantiga GS: VCC_SM ICH9M:PCIE_ICH ICH9M:SATA_ICH ICH9M:VCC_GLAN Mini Card: Express Card:	1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.71V-1.8V-1.89V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V 1.425V-1.5V-1.575V	130mA 0.5mA 60.31mA 35mA 485mA 149.5mA 3.1625A 646mA 1.342A 80mA 650mA
1.5V	Cantiga GS: DDRIII System Memory	1.425V-1.5V-1.575V	3.1A(800M) 4.1A(1067M)
0.75VDDT_DDRIII	Terminator:	0.7125V-0.75V-0.7875V	1.0A
3VS	Cantiga GS: HV CMOS Cantiga GS: VCCS_TV DAC ICH9M:VCC3_3 ICH9M:VCCGLAN3_3 Thermal Sensor: Mini Card: UMTS Express Card: CLK Generator: ICS9LPRS365BKLF Mini Card: WirelessLan Bluetooth: Super I/O: IT8305E Azalia Codec: ALC262 Azalia MDC:	3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.0V-3.3V-3.6V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V	105.3mA 78mA 308mA 1mA 5mA 1.3A 500mA
1.8VS	DVI	3.0V-3.3V-3.6V	120mA
3VA	ICH9M: RTC ICH9M:VCCSUS3_3 ICH9M:VCCCL3_3 ICH9M:VCCLAN3_3 LCD: Lan:AR8131 Azalia MDC: Flash ROM: BIOS	2V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.135V-3.3V-3.465V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V 3.0V-3.3V-3.6V	6uA 212mA 73mA 78mA 2A 1A
5VS	Cardreader: RTS5159 Azalia Codec: ALC269 HDD: SATA HDD: SATA HDD: SATA Audio AMP: G1432 Inverter: WebCam	3.0V-3.3V-3.6V 3.0V-3.3V-3.6V 4.75V-5.0V-5.25V 4.75V-5.0V-5.25V 4.75V-5.0V-5.25V 4.75V-5.0V-5.25V	Max: 1.5A ; R/W: 460mA ; STDBY: 70mA Max: 1.5A ; R/W: 900mA ; STDBY: 45mA
5VA	USB: x 2 ports USB	5VA 5VA	1A 2A 1.5A
5VLA	Control Power		
3VLA	EC: ITE8512E	3.0V-3.3V-3.6V	300mA

INVENTEC			
TITLE: BAP31 (Penryn+Cantiga+ICH9M)SFF			
ANNOTATIONS			
SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A2264501ALG	X01
CHANGE by		DATE	SHEET
Miles Lu		Tuesday, March 10, 2009	4 of 36

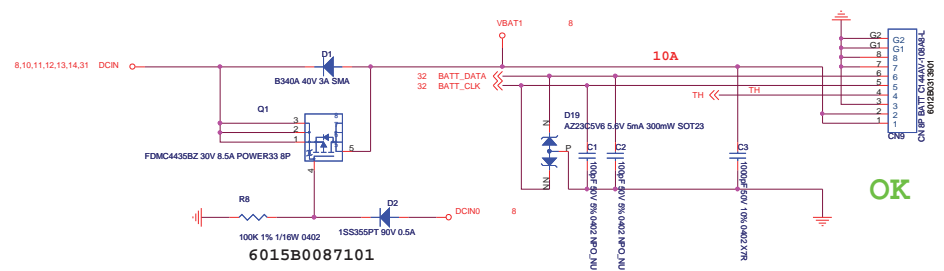
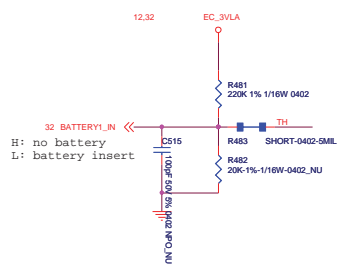
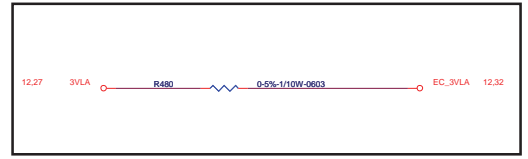
Power Block Diagram :

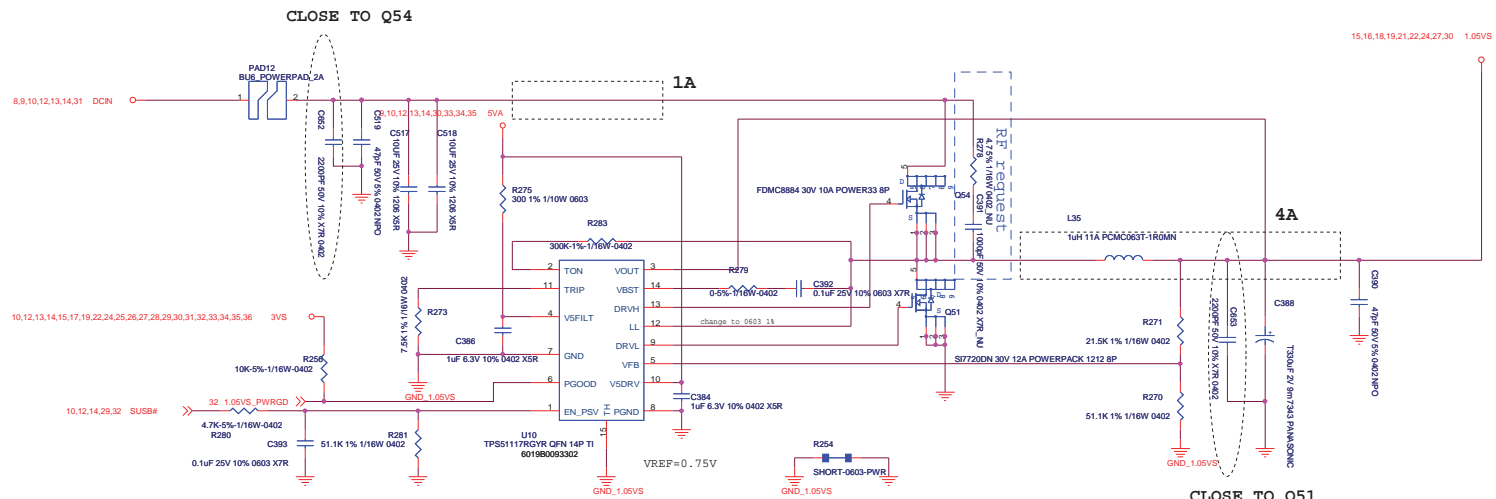
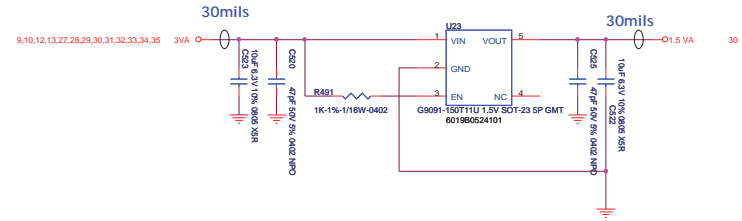
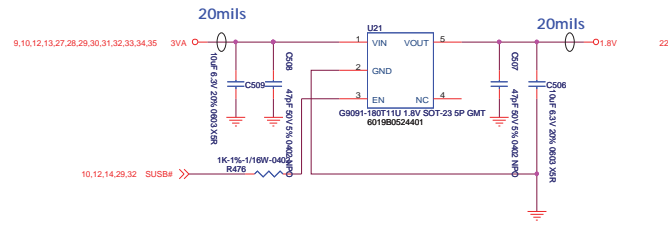


INVENTEC			
TITLE: BAP31 (Penryn+Cantiga+ICH9M)SFF			
Power Block Diagram			
SIZE	CODE	DOC NUMBER	REV
C	X01	D-CS-1310A2264501A1G	X01
CHANGE BY: Miles Lu		DATE: Tuesday, March 10, 2009	SHEET: 7 of 36



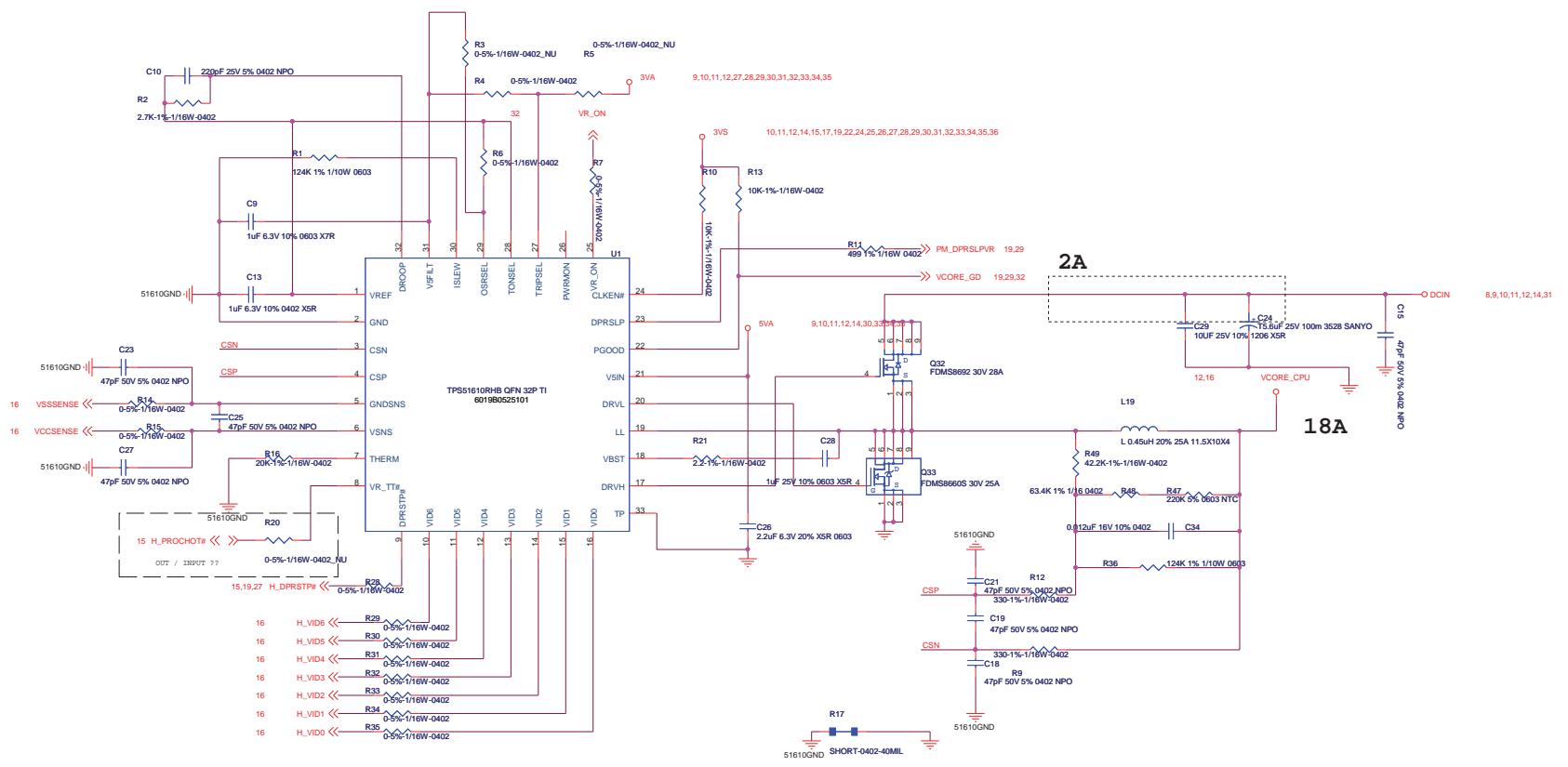
For Green PC





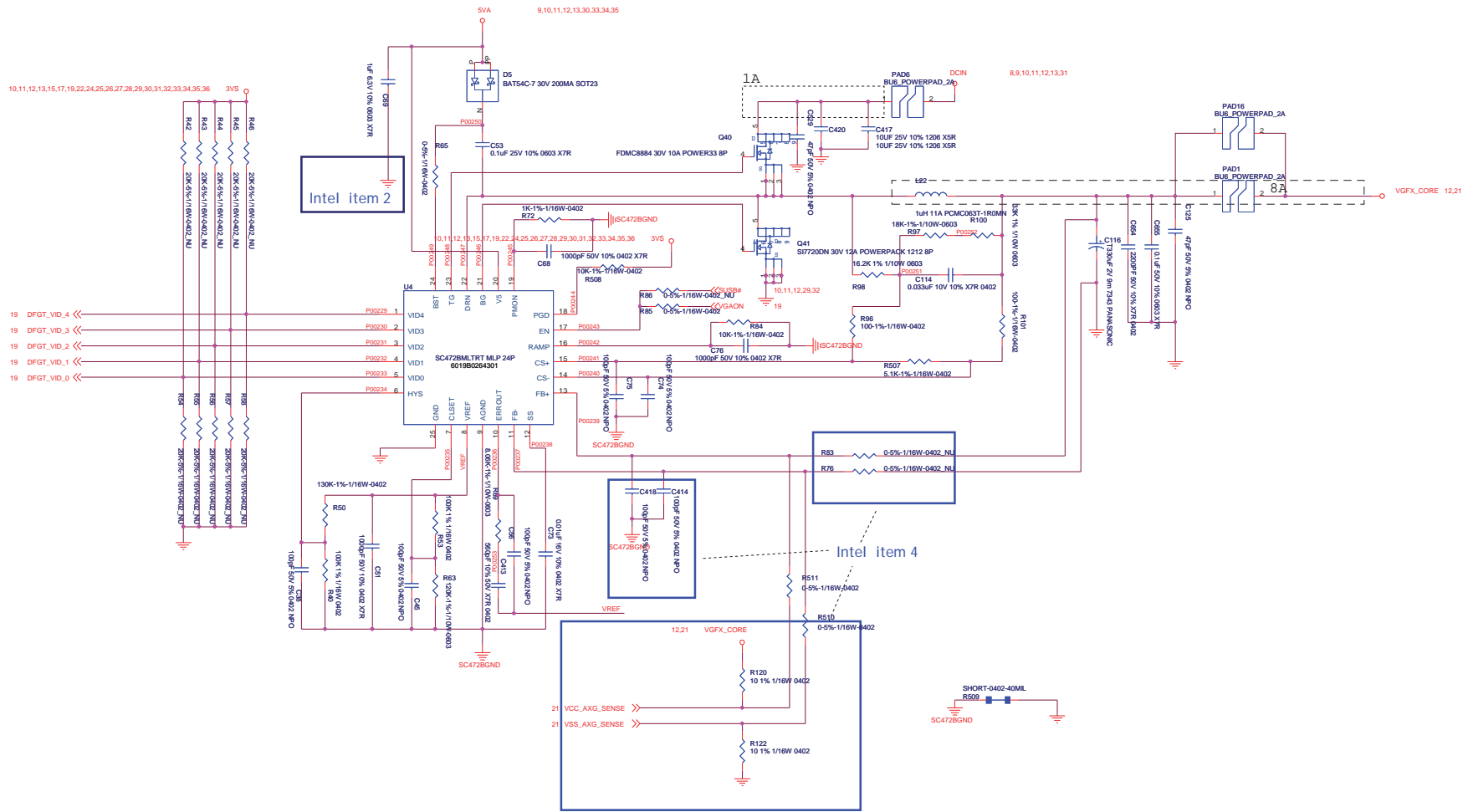
<http://laptop-motherboard-schematic.blogspot.com/>

INVENTEC			
TITLE BAP31 (Penryn+Contiga+ICH9M) SF1			
1.05VS/1.5V/1.8V/1.5VA			
SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A2284501-ALG	X01
CHANGE by Miles Liu		DATE Tuesday, March 10, 2009	SHEET 11 of 36



<http://laptop-motherboard-schematic.blogspot.com/>

INVENTEC			
TITLE: EAP31 (Penryn+Cantiga+ICH9M)SFF CPU Core Power			
SIZE	CODE	DOC NUMBER	REV
c	001	D-CS-1310A228491-ALG	001
CHANGE by: Miles Liu		DATE: Tuesday, March 10, 2009	SHEET: 13 of 35

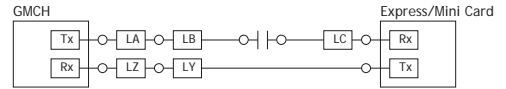
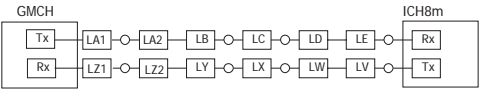
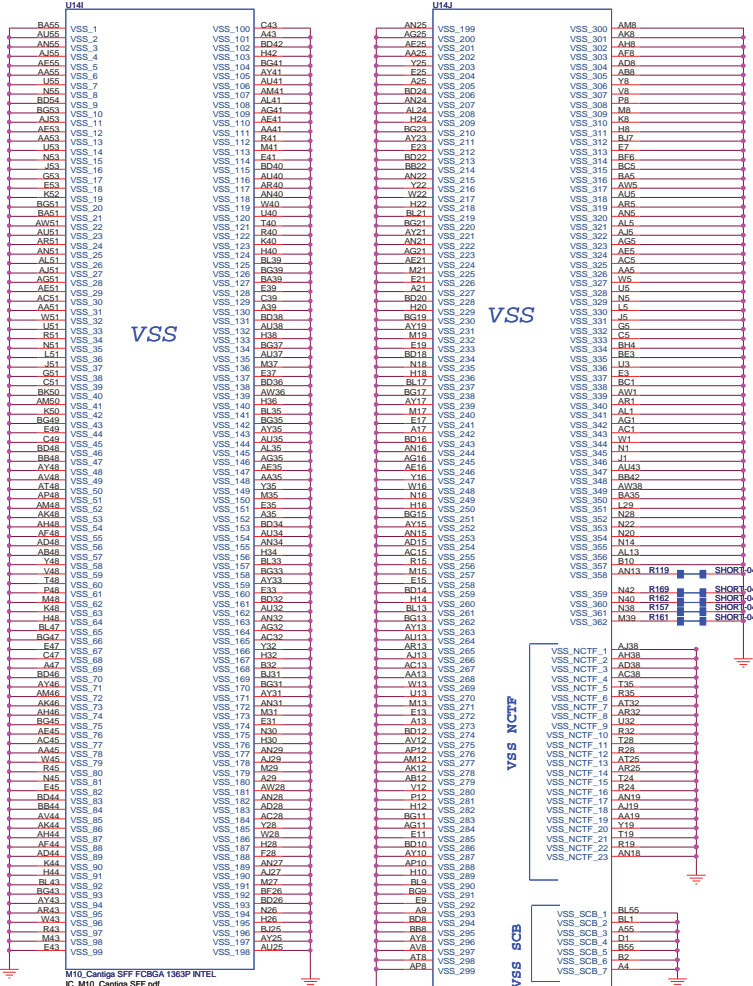


<http://laptop-motherboard-schematic.blogspot.com/>

INVENTEC			
TITLE: BAP31 (Penryn+Contiga+ICH9M) SF			
GPU CORE			
SIZE	CODE	DWG. NUMBER	REV
Custom	X01	D-CS-1310A2264501-ALG	X01
CHANGE by	Miles Liu	DATE	Tuesday, March 10, 2009
SHEET		14	of 36

DMI Routing Guideline

PCIe Routing Guideline



Breakout/in LA/LZ	Main Route	Main Route	Breakout/in LE/LV
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Stripline
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Microstrip	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Stripline
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Stripline
Stripline	Same Routing layer as LA/LZ	Same Routing layer as LE/LV	Microstrip

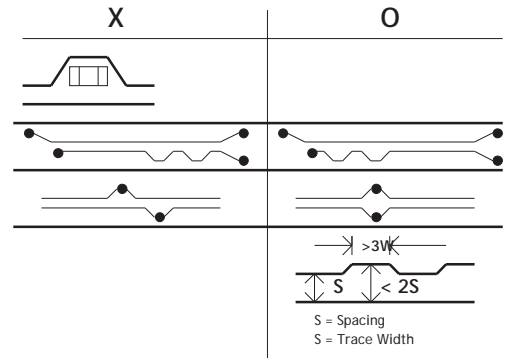
Breakout/in LA/LZ	Main Route	Main Route	Breakout/in LE/LV
Stripline	Microstrip	Same Routing layer as LE/LV	Microstrip

Parameter	Main Route Guideline	Breakout Guideline
Uncoupled Single End Impedance	55 +/- 15%	55 +/- 15%
Nominal Trace Width	Inner Layer : 4 mils Outer Layer : 5 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Nominal Diferential Pair-Pitch	Inner Layer : 7 mils Outer Layer : 7 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Pair-to-Pair Pitch	Inner Layer : 37 mils Outer Layer : 37 mils	Inner Layer : 27 mils Outer Layer : 27 mils
Bus-to-Bus Pitch	Inner Layer : 22 mils Outer Layer : 20 mils	Inner Layer : 15 mils Outer Layer : 12 mils
Reference Plane	Ground	Ground
Splits/Voids	No routing over plane splits No routing over voids	No routing over plane splits No routing over voids
Trace Length-LA (ICH7m Breakout)	Max = 400 mils	
Trace Length-LB (ICH7m Breakout to AC cap)	Max = 10750 mils	
Trace Length-LC (AC cap to PCIe CN)	Max = 10750 mils	
Trace Length-L1 (LA+LB+LC)	Max = 12000 mils	
Trace Length-LY (PCIe CN to ICH7m Breakout)	Max = 11950 mils	
Trace Length-LZ (ICH7m Breakout)	Max = 400 mils	
Trace Length-L2 (LY+LZ)	Max = 12000 mils	

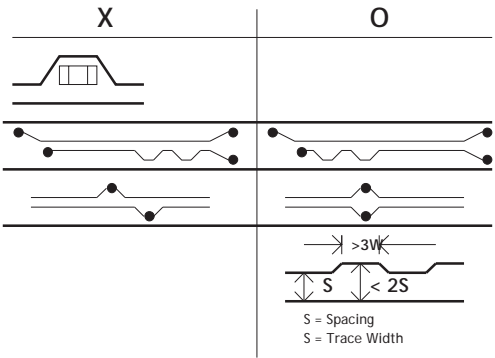
Parameter	Main Route Guideline	Breakout Guideline
Uncoupled Single End Impedance	55 +/- 15%	55 +/- 15%
Nominal Trace Width	Inner Layer : 4 mils Outer Layer : 5 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Nominal Diferential Pair-Pitch	Inner Layer : 7 mils Outer Layer : 7 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Pair-to-Pair Pitch	Inner Layer : 37 mils Outer Layer : 37 mils	Inner Layer : 27 mils Outer Layer : 27 mils
Bus-to-Bus Pitch	Inner Layer : 22 mils Outer Layer : 20 mils	Inner Layer : 15 mils Outer Layer : 12 mils
Reference Plane	Ground	Ground
Splits/Voids	No routing over plane splits No routing over voids	No routing over plane splits No routing over voids
Trace Length-LA (GMCH Breakout)	Max = 250 mils	
Trace Length-LB (GMCH Breakout to Via2)	Max = 3600 mils	
Trace Length-LC (Via2 to Via3)	Max = 5900 mils	
Trace Length-LD (Via3 to ICH7m Breakout)	Max = 3600 mils	
Trace Length-LE (ICH7m Breakout)	Max = 400 mils	
Trace Length-L1 (LA+LB+LC+LD+LE)	Max = 8000 mils	
Trace Length-LV (ICH7m Breakout)	Max = 400 mils	
Trace Length-LW (ICH7m Breakout to Via2)	Max = 3600 mils	
Trace Length-LX (Via2 to Via3)	Max = 5900 mils	
Trace Length-LY (Via3 to GMCH Breakout)	Max = 3600 mils	
Trace Length-LZ (GMCH Breakout)	Max = 400 mils	
Trace Length-L2 (LV+LW+LX+LY+LZ)	Max = 8000 mils	

*** When routing near the edge of their reference plane , trace should maintain at least 40 mils space to the edge of the plane
 *** Match the trace lengths of the complementary signals within each differential pair to +/- 5 mils

Parameter	Main Route Guideline	Breakout Guideline
Uncoupled Single End Impedance	55 +/- 15%	55 +/- 15%
Nominal Trace Width	Inner Layer : 4 mils Outer Layer : 5 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Nominal Diferential Pair-Pitch	Inner Layer : 7 mils Outer Layer : 7 mils	Inner Layer : 4 mils Outer Layer : 5 mils
Pair-to-Pair Pitch	Inner Layer : 37 mils Outer Layer : 37 mils	Inner Layer : 27 mils Outer Layer : 27 mils
Bus-to-Bus Pitch	Inner Layer : 22 mils Outer Layer : 20 mils	Inner Layer : 15 mils Outer Layer : 12 mils
Reference Plane	Ground	Ground
Splits/Voids	No routing over plane splits No routing over voids	No routing over plane splits No routing over voids
Trace Length-LA (GMCH Breakout)	Max = 250 mils	
Trace Length-LB (GMCH Breakout to Via2)	Max = 3600 mils	
Trace Length-LC (Via2 to Via3)	Max = 5900 mils	
Trace Length-LD (Via3 to ICH7m Breakout)	Max = 3600 mils	
Trace Length-LE (ICH7m Breakout)	Max = 400 mils	
Trace Length-L1 (LA+LB+LC+LD+LE)	Max = 8000 mils	
Trace Length-LV (ICH7m Breakout)	Max = 400 mils	
Trace Length-LW (ICH7m Breakout to Via2)	Max = 3600 mils	
Trace Length-LX (Via2 to Via3)	Max = 5900 mils	
Trace Length-LY (Via3 to GMCH Breakout)	Max = 3600 mils	
Trace Length-LZ (GMCH Breakout)	Max = 400 mils	
Trace Length-L2 (LV+LW+LX+LY+LZ)	Max = 8000 mils	



*** When routing near the edge of their reference plane , trace should maintain at least 40 mils space to the edge of the plane
 *** Match the trace lengths of the complementary signals within each differential pair to +/- 5 mils

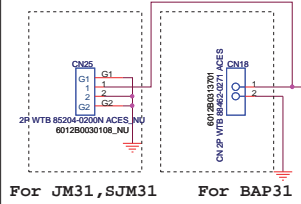


INVENTEC
 TITLE: BAP31 (Penryn+Cantiga+ICH9M)SFF
 Cantiga Ground(6/6)
 DOC NUMBER: D-CS-1310A2264501-ALG
 SHEET: 23 of 36
 CHANGE by: Miles Lu DATE: Tuesday, March 10, 2009

RTC Circuit

1. RC delay time should be in the range of 18-25ms
2. It is recommended that this larger capacitor and small resistor value in order to reduce the likelihood of glitching of RTRCRST#

1. The ICH7m requires a length less than 1 inch on each branch (from crystal's terminal to RTCXn ball)
2. Routing the RTC circuit should be kept simple to simplify the trace length measurement and increase accuracy on calculating trace capacitances
3. On FR-4, a 5-mils trace has approximately 2pF per inch
4. Trace signal coupling must limited as much as possible by avoiding the routing of adjacent PCI signals close to RTCX1 and RTCX2
5. Ground guard plane is highly recommended



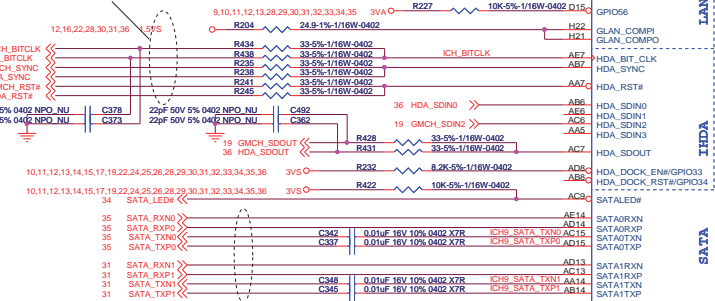
For Green PC



123
CABLE_ROUND_3POS_75mm.I_RTC_NU
6027B0066801

RTC Battery Life :
220mAh(220000uAh) / 6uA = 4.2 year

Place all series resistors 0.6 to 2.6 inches from the ICH9



Distance between the ICH9-M and cap on the "P" signal should be identical distance between the ICH9-M and cap on the "N" signal for same pair.

Placed within 500mils of ICH9m ball

Needs to be placed within 2" of ICH9m

Must be placed within 2" of 24.9 ohm w/o stub

ICH8m internal VR enable strap

INTVRMEN	Enable	Disable
	1(Default)	0

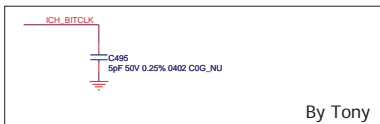
Internal VRM enabled for VccSus1_05, VccSus1_5, VccCL1_5, VccLAN1_05 and VccCL1_05

AC2_SDATAOUT strap functionality base on RSVD9 strap
XOR chain entrance (RSVD9 pulled low)
PCIe port config bit 1 (RSVD9 not pulled low)

Stuff for XOR chain testing

ICH9M TP#	IC8M SDOUT#	Description
0	0	Enter XOR Chain
1	0	Normal Operation (default)
1	1	Set PCIe port config bit

Short pins AG1 and AG2 at the package



By Tony

<http://laptop-motherboard-schematic.blogspot.com/>

INVENTEC

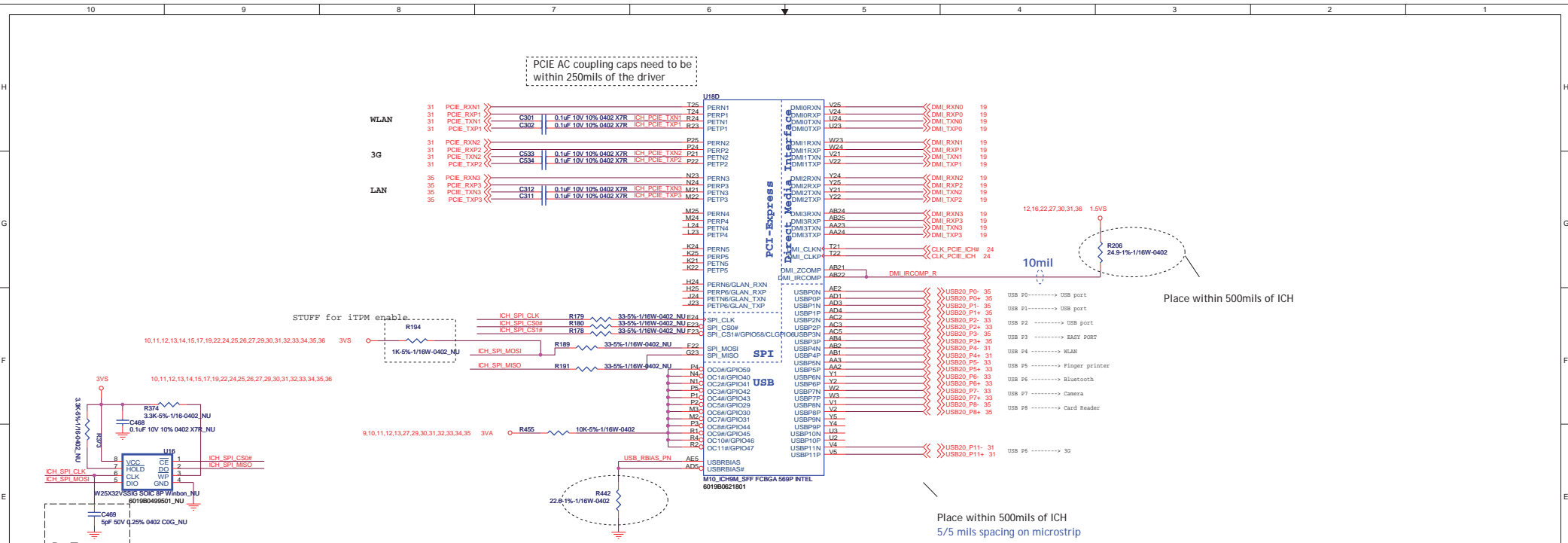
FILE: BAP31 (Penryn+Cantiga+ICH9M)SFF

IC: ICH9M CPU/IDE/SATA(14)

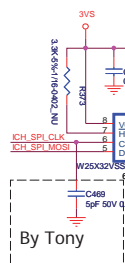
SIZE	CODE	DOC NUMBER	REV
Custom	X01	P-CS-1310A2284501-ALG	X01

CHANGE by Miles Liu DATE Tuesday, March 10, 2009 SHEET 27 of 36

PCIe AC coupling caps need to be within 250mils of the driver



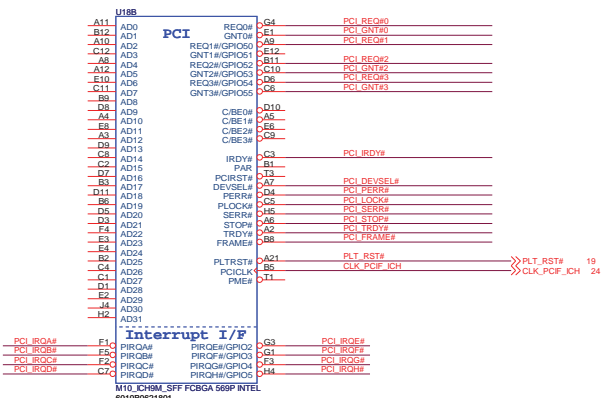
STUFF for iTPM enable



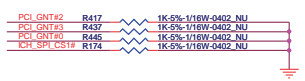
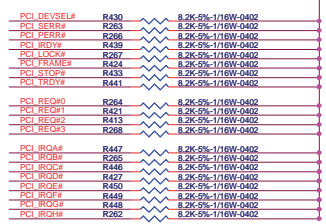
10mil

Place within 500mils of ICH

Place within 500mils of ICH
5/5 mils spacing on microstrip

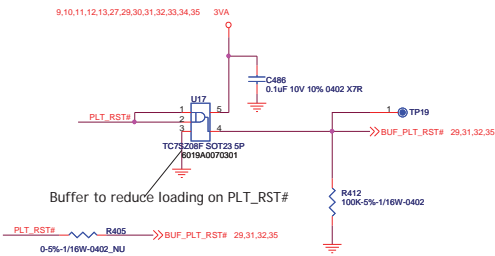


PCI Pull up



PCI_GNT#3 No stuff : by default
Stuff : For A16 swap override

PCI_GNT#0	SPT_CST#	LPC
1	1	LPC
1	0	PCI
0	1	SPI



Check BIOS type

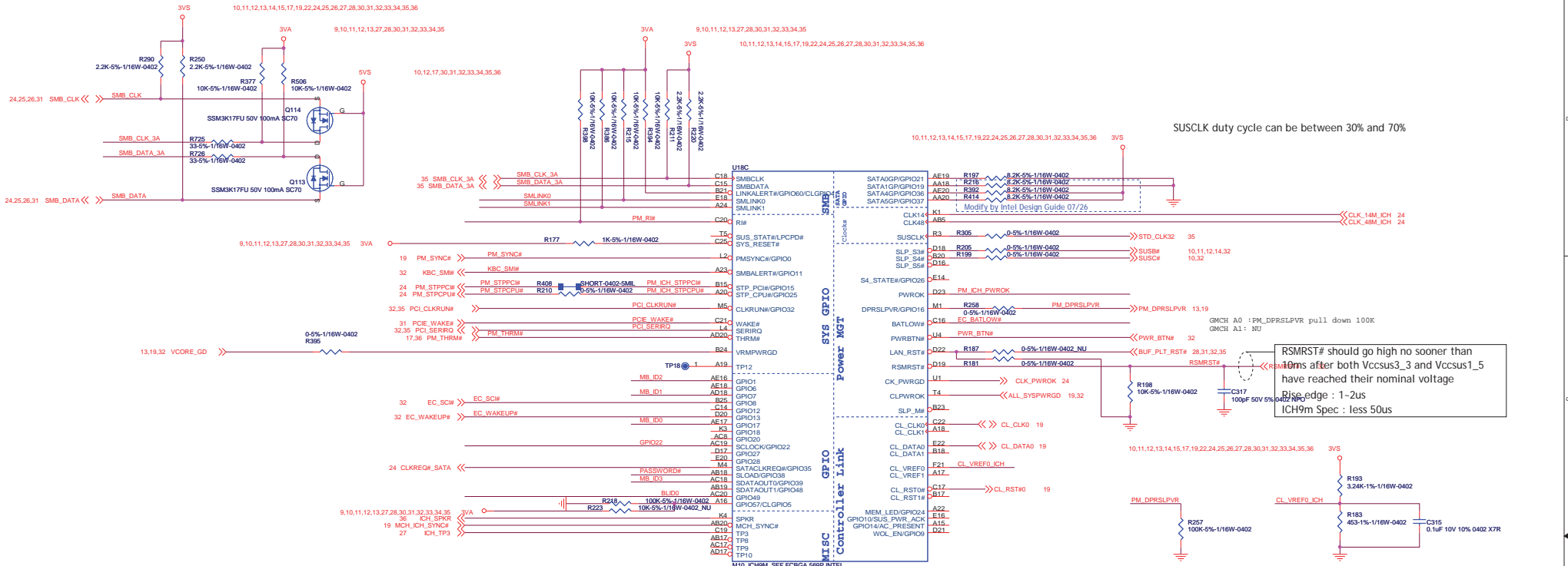
<http://laptop-motherboard-schematic.blogspot.com/>

INVENTEC

TITLE: BAP31 (Penryn+Centiga+ICH9M)SFF ICH9M PCI/PCIE/DMI/USB(24)

SIZE	CODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A2264501-ALG	X01

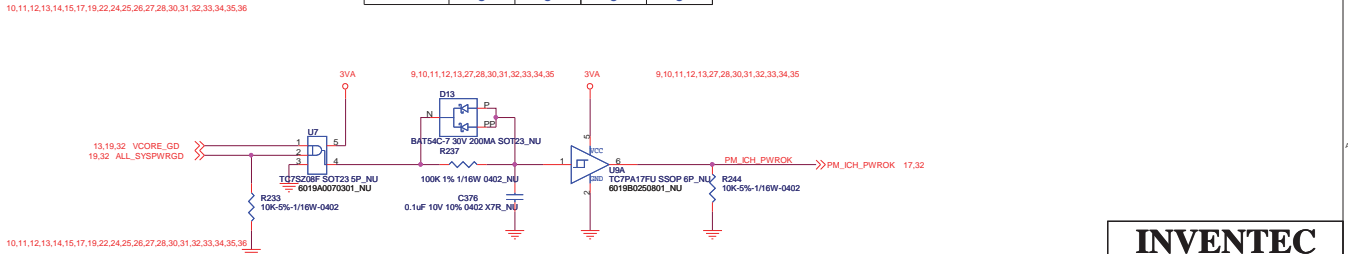
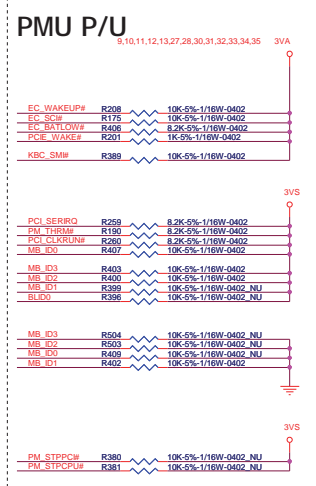
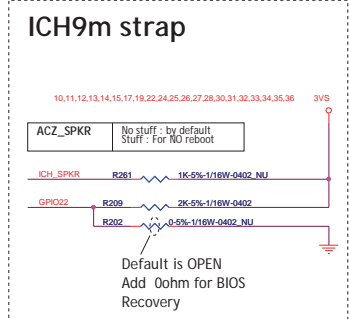
CHANGE by Miles Liu DATE Tuesday, March 10, 2009 SHEET 28 of 38



RSMRST# should go high no sooner than 10ms after both Vccs3_3 and Vccs1_5 have reached their nominal voltage
 Rise edge : 1-2us
 ICH9m Spec : less 50us

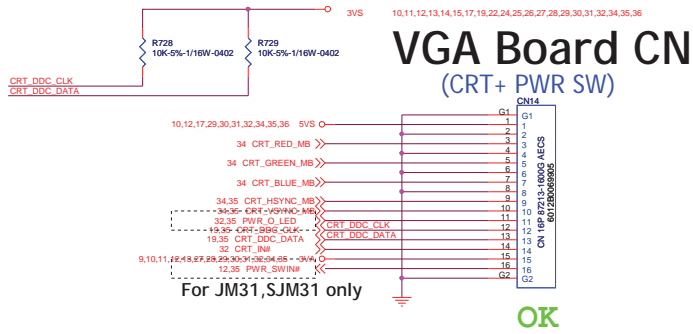
BIOS ID setting

Project	MB_ID3	MB_ID2	MB_ID1	MB_ID0
JM31 (UMA)	1	1	1	1
SJM31 (UMA)	1	1	1	0
BAP31 (UMA)	1	1	0	1
	1	1	0	0
	1	0	1	1
	1	0	1	0
	0	1	1	1
	0	1	1	0
	0	1	0	1
	0	1	0	0
	0	0	1	1
	0	0	1	0
	0	0	0	1
	0	0	0	0

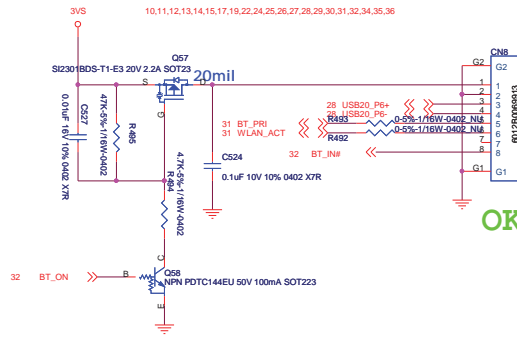


<http://laptop-motherboard-schematic.blogspot.com/>

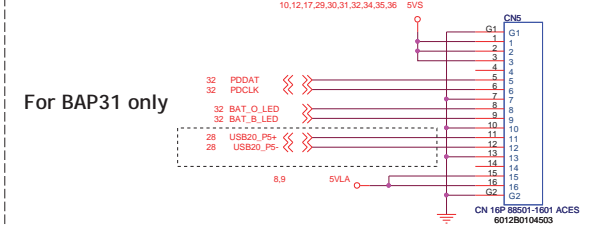
INVENTEC
 TITLE: BAP31 (Penryn+Cantiga+ICH9M)SFF
 ICH9M GPIO(34)
 SIZE: Custom CODE: X01 DOC NUMBER: D-CS-1310A2264501ALG REV: X01
 SHEET: 29 of 36



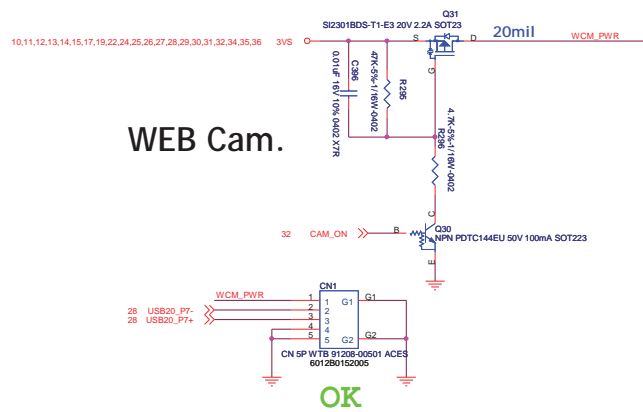
Bluetooth CON.



GLIDE PAD Board

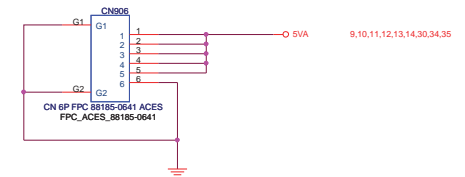
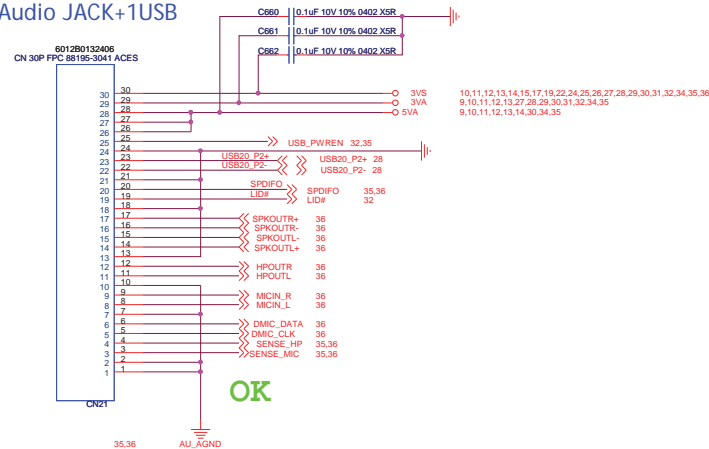


WEB Cam.



AUDIO Board CN

(Audio JACK+1USB)



INVENTEC

TITLE BAP31 (Penryn+ Cantiga+ ICH9M)SE
Daughter Connector

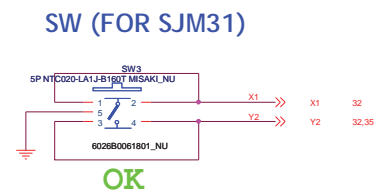
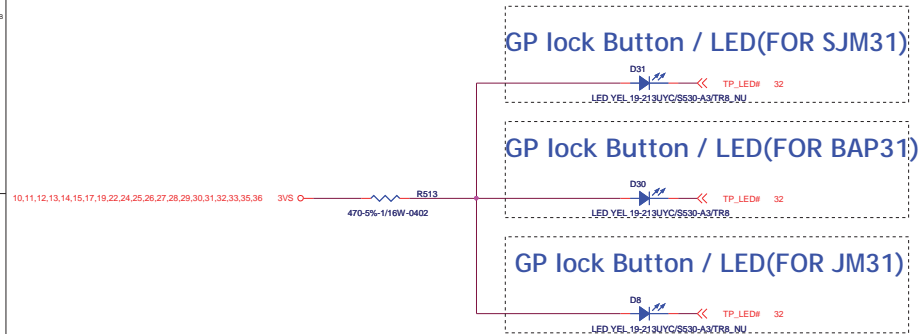
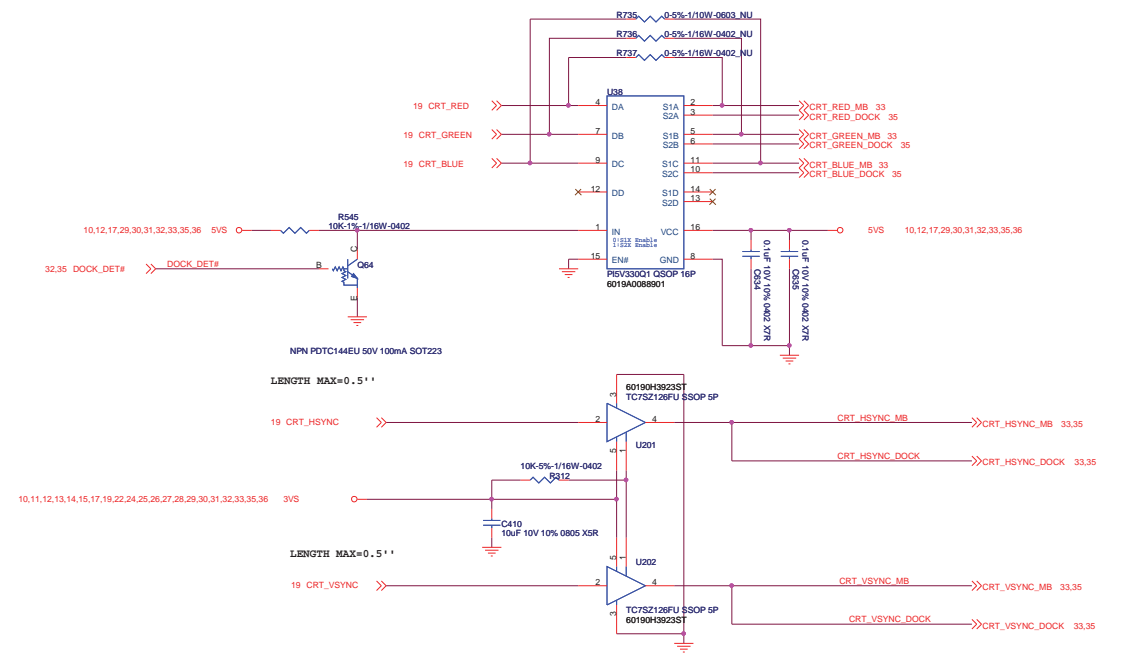
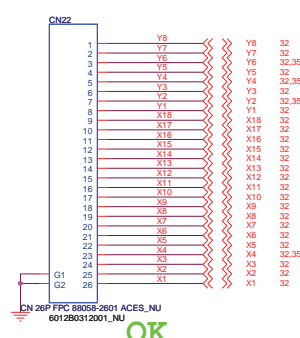
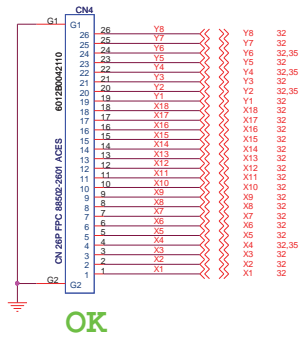
SIZE	CCODE	DOC NUMBER	REV
Custom	X01	D-CS-1310A2264501-ALG	X01

CHANGE by Miles Liu DATE Tuesday, March 10, 2009

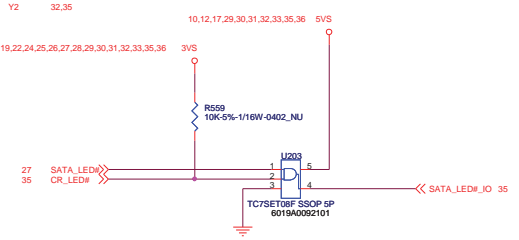
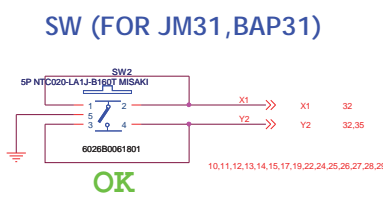
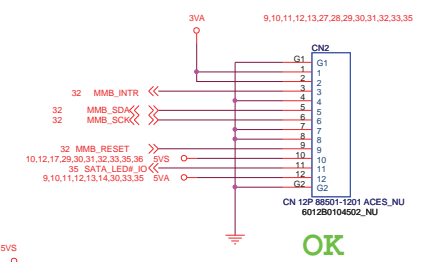
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To K/B(For JM31,BAP31)

To K/B (For SJM31)

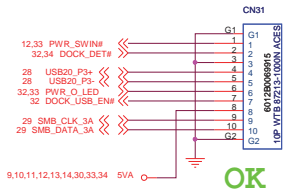


SW Sensor BOARD(For JM31,SJM31)

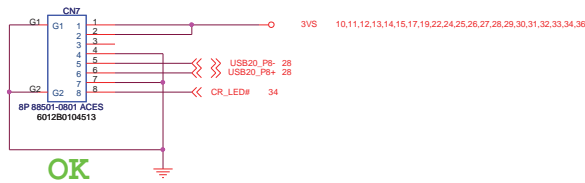


INVENTEC			
TITLE BAP31 (Penryn+Cantiga+ICH9M)SFF BDP			
SIZE	CCODE	DOCNUMBER	REV
Custom	X01	D-CS-1310A224501-AL-G	X01
SHEET			34 of 36

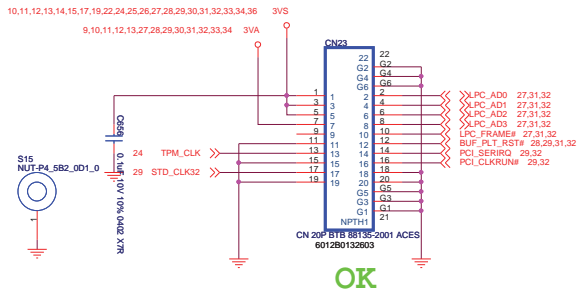
MB(USB) TO EASY/B



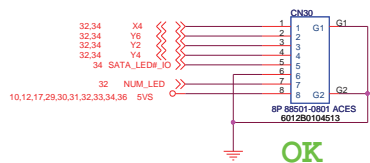
Card Reader BOARD CN



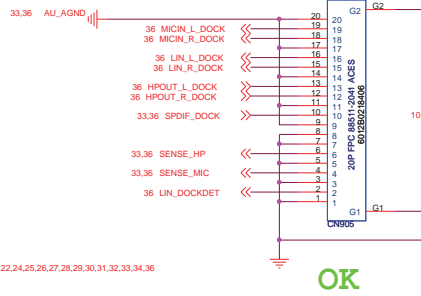
TPM CN



SW/B CN

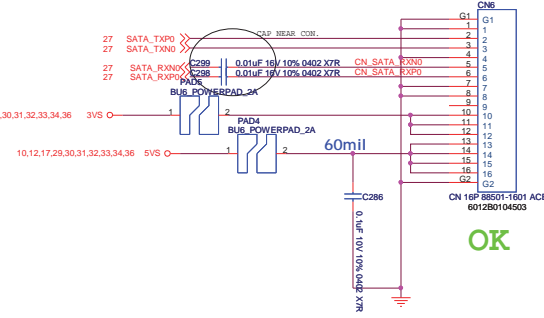


MB(AUDIO) TO EASY/B(For BAP31)

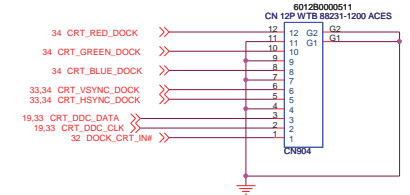


For BAP31(EASY/B)

SSD I/F



MB(RGB) TO EASY/B



USB Board CN (LAN+HDMI+2USB)

